# <u>TXGA</u>

### Board to board connector Pitch 0.5mm series

## 1. Scope

Board to board Connector pitch 0.5mm series This specification covers the Board to board connector pitch 0.5mm series

## 2. Ordering information

Refer to the drawing.

### 3. Connector dimensions

Refer to the drawing.

### 4. Material

Housing: Heat resistant polymer (UL 94V-0)

Color :Refer to the drawing

Terminal: Phosphor bronze

Plating:Gold plated

# 5. Accommodated P.C.B layout

Refer to the drawing.

## 6. Rating

Operating voltage(Max.)	50V DC
Current rating(Max.)	0.5A Max. (Each Circuit)
Temperature range-operating	-25°C +85°C(Including terminal temperature rise)

#### 7. Performance

#### **Electrical Performance**

Contact Resistance	40mΩ Max	Mate The sample connectors, measure by dry circuit, 20mV Max., 100mA Max. (EIA-364-23)				
Insulation Resistance	100MΩ Min	Unmated The sample connectors, apply 500V DC between adjacent terminal or ground. (EIA-364-21)				
Dielectric Strength	No Breakdown. Current leakage: 1 mA Max.	Unmated The sample connectors, Apply 250V AC for 1minute. Test between adjacent circuit of unmated connector. (EIA-364-20)				

#### **Mechanical Performance**

Lierminal Refention Force		Load shall be applied on each at a speed of 25±3mm/minute as sh below then pin retention force shall be measured.						
LINSETTION FORCE		Mate The sample connectors shall be soldered on a board and inserted and separated at speed of 25±3mm/min. (EIA-364-13)						

#### **Environmental Performance and others**

	Mate The sample connectors should be mounted in the tester and fully mated and unmated the number	Appearance	No Damage	
Durability	of 30cycles specified at the rate of 25±3 mm/min. (EIA-364-09)	Contact Resistance	90mΩ Max	

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Vibration	Mate connectors and subject to the following vibration conditions for period of 2 hours in each of 3 mutually perpendicular axes passing DC 1mA	Appearance	No Damage					
	during the test. Amplitude:1.5mm P-P frequency:10~55~10 Hz in 1 minute	Contact Resistance	90mΩ Max					
	(EIA-364-28 Condition I)	Discontinuity	1µsec Max					
	Mate The sample connectors shall and subject to the following shock condition.3 times of shocks shall be applied for each 6 directions along 3 mutually	Appearance	No Damage					
Shock	perpendicular axes, passing DC 1mA current during the test.(Total of 18 shocks) Peak	Contact Resistance	90mΩ Max					
	value490m/s2{50G} (EIA-364-27, test condition A)	Discontinuity	1µsec Max					
Temperature Rising	Mate The sample connectors and measure the temperature rise of contact when the maximum AC rated current is passed. (EIA-364-70 METHOD 2)	30°C Max. Under load	ded rating current					
Heat Resistance	Mate The sample connectors shall expose to 85±2° C for 96 hours. Upon completion of the exposure	Appearance	No Damage					
	period, the test specimens shall be conditioned at ambient room condition for 1 to 2 hours, after which the specified measurements shall be performed.	Contact Resistance	90mΩ Max					
Cold Resistance	Mate The sample connectors shall expose to -25±2° C for 96 hours. Upon completion of the exposure period, the test specimens shall be conditioned at	Appearance	No Damage					
	ambient room condition for 1 to 2 hours, after which the specified measurements shall be performed.	Contact Resistance	90mΩ Max					
	Mate The sample connectors shall expose to 40±2°	Appearance	No Damage					
	C relative humidity 90~95% for 96 hours. Upon completion of the exposure period, the test	Contact Resistance	90mΩ Max					
Humidity	specimens shall be conditioned at ambient room condition for 1 to 2 hours, after which the specified measurements	Dielectric strength	No Breakdown					
	shall be performed.	Insulation Resistance	500MΩ Min					
Temperature Cycling	A connector shall and subject to the following condition for 5 cycles .Upon completion of the exposure period, the test specimens shall be conditioned at ambient room condition for 1to2	Appearance	No Damage					
	hours, after which the specified measurements shall be performed. 1cycle a)-25±3°C,30 minutes b) +85±3°C,30 minutes (Transit time shall be with in 3 minutes ) (EIA-364-31, Test condition A)		90mΩ Max					
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STANDARD SPECIFICATION



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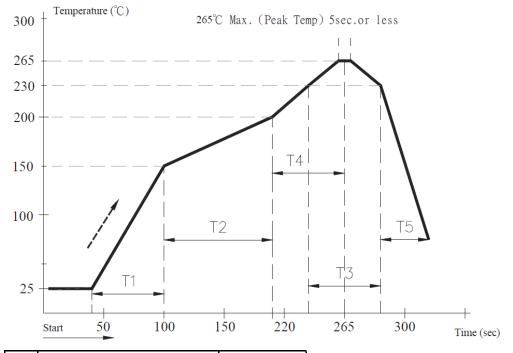
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Salt Spray	Mate The sample connectors shall expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water, after which the specified NaCl solution Concentration:5±1% Spray time:24hours Ambient temperature:35±2°C (EIA-364-26,Test condition B)	Appearance	No Damage					
Solderability	Tip of solder tails and fitting mails into the molten solder (held at 265±5°C) up to 0.1mm from the Housing for 3±0.5sec onds. (EIA-364-52)	Solder Wetting	95% ofimmersed area must show no voids ,pin holes					
Resistance to Soldering Heat			No Damage					

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#### 8. Infrared reflow condition



T1	Temperature ramp up rate	2°C5°C/Sec
T2	Preheat: 150°C200°C	6090Sec
Т3	Time over 230°C	3050Sec
T4	Preheat: 200°C250°C	30Sec
T5	Ramp down rate during cooling	4°C7°C/Sec
	Peak temperature	265°C Max.

Temperature condition graph

Temperature on board pattern side

# 9. Product qualification and reliability test sequence

Test or Examination		Test Group										
		В	С	D	Е	F	G	Н	I	J	Κ	L
Appearance	1;7	1;3	1;6	1;6	1;6	1;3	1;6	1;6	1;5	1;5	1;3	1;3
Contact Resistance			2;5	2;5	2;5		2;5	2;5	2;4	2;4		
Dielectric Withstanding Voltage	3;6											
Insulation Resistance	2;5											
Insertion Force		2										
Contact Retention Force			3;4									
Vibration				3;4								
Shock Mechanical					3;4							
Temperature Rising						2						
Heat Resistance							3;4					
Cold Resistance								3;4				
Humidity	4											
Temperature Cycling									3			
Salt Spray										3		
Solder ability											2	
Resistance to Soldering Heat												2

STANDARD SPECIFICATION